TOSHIBA BiCD Integrated Circuit Silicon Monolithic

TB7107FN

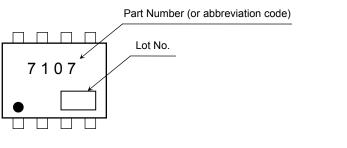
Buck DC-DC Converter IC

The TB7107FN is a single-chip buck DC-DC converter IC utilizing a chopper circuit. The TB7107FN adopts bootstrap system and contains high-speed and low-on-resistance N-channel MOSFETs for the high side main switch to achieve high efficiency.

Features

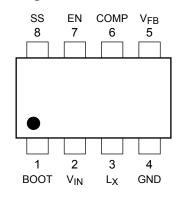
- Enables up to 2 A of load current (IOUT) with a minimum of external components.
- High efficiency: $\eta = 87\%$ (typ.) (@VIN = 12 V, VOUT = 3.3 V and IOUT = 0.7A)
- Operating voltage range: V_{IN} = 4.5 V to 20 V
- Low ON-resistance: RDS (ON) = 0.2Ω (high-side) typical (@VIN = 12 V, Tj = 25° C)
- Oscillation frequency: fOSC = 380 kHz (typ.)
- Reference voltage: $V_{FB} = 0.8 \text{ V} \pm 2.25\%(@ \text{ T}_{j} = 25 \degree\text{C})$
- Because of an external phase compensation element, the optimal phase compensation according to the output filter capacitor can be realized.
- Allows the use of a small surface-mount ceramic capacitor as an output filter capacitor.
- Housed in a small surface-mount package (PS-8) with low thermal resistance.
- Soft-start time adjustable by an external capacitor

Part Marking

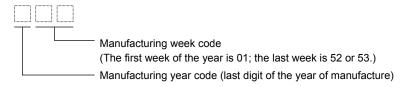


The dot ($\bullet)$ on the top surface indicates pin 1.

Pin Assignment

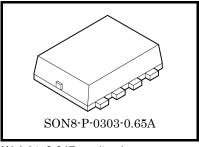


*: The lot number consists of three digits. The first digit represents the last digit of the year of manufacture, and the following two digits indicates the week of manufacture between 01 and either 52 or 53.



This product has a MOS structure and is sensitive to electrostatic discharge. Handle with care.

The product(s) in this document ("Product") contain functions intended to protect the Product from temporary small overloads such as minor short-term overcurrent, or overheating. The protective functions do not necessarily protect Product under all circumstances. When incorporating Product into your system, please design the system (1) to avoid such overloads upon the Product, and (2) to shut down or otherwise relieve the Product of such overload conditions immediately upon occurrence. For details, please refer to the notes appearing below in this document and other documents referenced in this document.

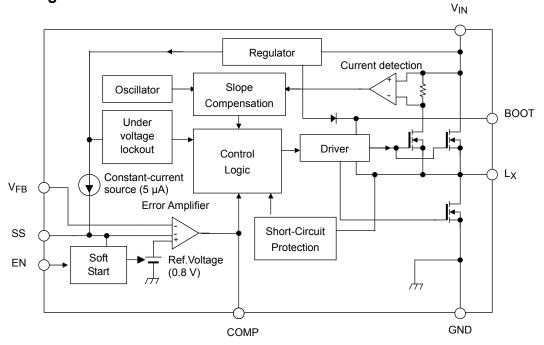




Ordering Information

Part Number	Shipping
TB7107FN (TE85L, F)	Embossed tape (3000 units per reel)

Block Diagram



Pin Description

Pin No.	Symbol	Description
1	BOOT	Bootstrap pin
' 		This pin is connected to Bootstrap capacitor. A 0.1 μ F bootstrap capacitor is required between BOOT pin and L _X pin.
2	V _{IN}	Input pin
		This pin is placed in the standby state if EN = low. Standby current is 60 μ A (@V _{IN} =12V) or less.
3	Lx	Switch pin
5	۲X	This pin is connected to high-side N-channel MOSFET.
4	GND	Ground pin
5	V _{FB}	Feedback pin
5		This input is fed into an internal error amplifier with a reference voltage of 0.8 V (typ.).
6	COMP	Phase compensation pin
0		Pin for connecting an error amplifier phase compensation resistor and capacitor.
	EN	Enable pin
7		When V _{EN} \geq 1.8 V (@ V _{IN} = 12 V), the internal circuitry is allowed to operate and thus enable the switching operation of the output section. When V _{EN} \leq 0.5 V (@ V _{IN} =12 V), the internal circuitry is disabled, putting the TB7107FN in Standby mode.
		This pin has an internal pull-up current of 15 µA(typ.).
	SS	Soft-start pin
0		The soft-start time can be adjusted with an external capacitor.
8		The external capacitor is charged from a 5 μ A (typ.) constant-current source, and the reference voltage of the error amplifier is regulated between 0 V and 0.8 V. The external capacitor is discharged when EN = low and in case of undervoltage lockout or thermal shutdown.

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Input pin voltage	V _{IN}	-0.3 to 25	V
Bootstrap pin voltage	V _{BOOT}	-0.3 to 28	V
Bootstrap pin - Switch pin voltage	V _{BOOT} -V _{LX}	-0.3 to 6	V
Switch pin voltage (Note 1)	V _{LX}	-0.3 to 25	V
Feedback pin voltage	V _{FB}	-0.3 to 6	V
Enable pin voltage	V _{EN}	-0.3 to 25	V
Soft-start pin voltage	V _{SS}	-0.3 to 6	V
Phase compensation pin voltage	VCOMP	-0.3 to 6	V
Switch pin current	I _{LX}	-2.3	А
Power dissipation (Note 2)	PD	0.9	W
Operating junction temperature	Tjopr	-40 to 125	°C
Junction temperature (Note 3)	Тj	150	°C
Storage temperature	T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

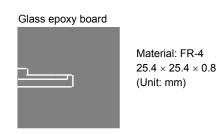
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc)

Note 1: The switch pin voltage (V_{LX}) doesn't include the peak voltage generated by TB7107FN's switching.

Thermal Resistance Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, junction to ambient	R _{th (j-a)}	110.2 (Note 2)	°C/W

Note 2:



Note 3: The TB7107FN may go into thermal shutdown at the rated maximum junction temperature. Thermal design is required to ensure that the rated maximum operating junction temperature, T_{jopr}, will not be exceeded.

Electrical Characteristics (Tj = 25°C, V_{IN} = 4.5 to 20 V, unless otherwise specified)

Characte	ristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Operating input volta	ge	V _{IN(OPR)}	—	4.5	_	20	V	
Operating current		l _{IN}	V _{IN} = 12V ,V _{EN} = 5V ,V _{FB} = 2 V		1.8	2.5	mA	
Output voltage range	•	V _{OUT(OPR)}	$V_{EN} = V_{IN}$	0.8		V _{IN} -2	V	
Standby current		I _{IN(STBY)}	V _{IN} = 12 V , V _{EN} = 0 V V _{FB} = 0.8 V	_	_	60	μA	
High-side switch leak	age current	I _{LEAK(H)}	V _{IN} = 12 V, V _{EN} = 0 V V _{FB} = 0.8 V , V _{LX} = 0 V			10	μA	
		V _{IH(EN)}	V _{IN} = 12 V	1.8 — -		—		
EN threshold voltage		V _{IL(EN)}	V _{IN} = 12V		0.5	V		
EN input ourrent		I _{IH(EN)}	V _{IN} = 12V, V _{EN} = 5 V	-5	_	5		
EN input current		I _{IL(EN)}	V _{IN} = 12V, V _{EN} = 0 V	_	-15	—	μA	
V _{FB} input voltage		V _{FB}	V _{IN} = 12 V , V _{EN} = 5 V	0.782	0.8	0.818	V	
V _{FB} input current		I _{FB}	V _{IN} = 12 V , V _{EN} = 5 V V _{FB} = 2V	-1	_	1	μA	
		I _{COMP(H)}	V _{IN} = 12 V , V _{EN} = 5 V V _{FB} = 0.7V , V _{COMP} = 0.5 V	_	-40	_		
Phase compensation	input current	I _{COMP(L)}	V _{IN} = 12 V , V _{EN} = 5 V V _{FB} = 0.9V , V _{COMP} = 0.5 V	_	40	_	μA	
High-side switch on-s	state resistance	RDS(ON)(H)	V _{IN} = 12V , V _{EN} = 5V I _{LX} = - 1A	_	0.2	_	Ω	
Low-side switch on-s	tate resistance	RDS(ON)(L)	V _{IN} = 12 V , V _{EN} =5 V I _{LX} = 100m A		1.5	_	Ω	
Oscillation frequency	,	fosc	V _{IN} = 12V , V _{EN} = 5V	300	380	460	kHz	
Internal soft-start time	e	tss	V_{IN} = 12 V , V_{EN} = 5V , I_{OUT} = 0A Measured between 0% and 90%points at V_{OUT}	0.5	1	2	ms	
External soft-start charge current		I _{SS}	V _{IN} = 12 V , V _{EN} = 5 V	-3	-5	-8	μA	
High-side switch duty cycle		Dmax	V _{IN} = 12 V , V _{EN} = 5 V	_	88		%	
Thermal shutdown	Detection temperature	T _{SD}	V _{IN} = 12 V , V _{EN} = 5 V	_	160	_	°C	
(TSD)	Hysteresis	ΔT _{SD}	V _{IN} = 12 V , V _{EN} = 5 V		15	15 —		
	Detection voltage	V _{UV}	V _{EN} = V _{IN}	2.9	3.2	3.5	- v	
Undervoltage lockout (UVLO)	Recovery voltage	V _{UVR}	V _{EN} = V _{IN}	3.2	3.5	3.8		
	Hysteresis	ΔV _{UV}	V _{EN} = V _{IN}	_	0.3	_		
L _X current limit	•	I _{LIM}	V _{IN} = 4.5V to 20 V , V _{EN} = 5V V _{OUT} = 2 V	2.9	3.5	_	A	

Note on Electrical Characteristics

The test condition $T_j = 25^{\circ}C$ means a state where any drifts in electrical characteristics incurred by an increase in the chip's junction temperature can be ignored during pulse testing.

Application Circuit Example

Figure 1 shows a typical application circuit using a low-ESR electrolytic or ceramic capacitor for C_{OUT} .

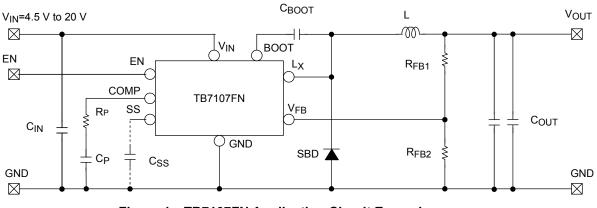


Figure 1 TB7107FN Application Circuit Example

Component values (reference value@ $V_{IN} = 12$ V, $V_{OUT} = 3.3$ V, $Ta = 25^{\circ}C$)

 C_{IN} : Input filter capacitor = 10 μ F

(ceramic capacitor: GRM31CR71E106K manufactured by Murata Manufacturing Co., Ltd.) COUT: Output filter capacitor = $10 \ \mu$ F

COUT: Output filter capacitor = $10 \ \mu F$

(ceramic capacitor: GRM31CR71E106K manufactured by Murata Manufacturing Co., Ltd.)

- R_{FB1} : Output voltage setting resistor = 7.5 k Ω
- RFB2: Output voltage setting resistor = 2.4 k Ω
- CP: Phase compensation capacitance
- $\operatorname{Rp}:$ Phase compensation resistance
- L: Inductor = 10 μH (SLF10165T-100M3R83PF or SLF7055T-100M2R5-3PF manufactured by TDK-EPC Corporation)

SBD: Schottky barrier diode CMS02 or CRS15 (manufactured by Toshiba Corporation)

 $C_{BOOT}: Bootstrap \ capacitor = 0.1 \ \mu F \ (GRM188R71H104J \ manufactured \ by \ Murata \ Manufacturing \ Co., \ Ltd.)$

 C_{SS} is a capacitor for adjusting the soft-start time.

Output Voltage Setting	Inductance		Feedback Resistor	Phase Compensation Capacitance	Phase Compensation Resistance		
V _{OUT}	L	C _{IN}	C _{OUT}	R _{FB1}	R _{FB2}	CP	R _P
1.2 V	10 μH	10 μF	20 μF	7.5 kΩ	15 kΩ	4700 pF	10 kΩ
1.51 V	10 μH	10 μF	20 μF	16 kΩ	18 kΩ	4700 pF	10 kΩ
1.8 V	10 μH	10 μF	20 μF	15 kΩ	12 kΩ	2200 pF	15 kΩ
2.5 V	10 μH	10 μF	20 μF	5.1 kΩ	2.4 kΩ	2200 pF	22 kΩ
3.3 V	10 μH	10 μF	20 μF	7.5 kΩ	2.4 kΩ	2200 pF	22 kΩ
5.0V	10 μH	10 μF	20 μF	27 kΩ	5.1 kΩ	2200 pF	33 kΩ

Examples of Component Values (For Reference Only)

 $Component \ values \ need \ to \ be \ adjusted, \ depending \ on \ the \ TB7107 FN's \ I/O \ conditions \ and \ the \ board \ layout.$

Application Notes

Inductor Selection

The inductance required for inductor L can be calculated as follows:

.....(1)

$$L = \frac{V_{IN} - V_{OUT}}{f_{OSC} \cdot \Delta I_L} \cdot \frac{V_{OUT}}{V_{IN}} \quad \cdots \cdots$$

VIN: Input voltage (V) V_{OUT}: Output voltage (V) f_{OSC}: Oscillation frequency = 380 kHz (typ.) ΔIL: Inductor ripple current (A)

*: Generally, ΔI_L should be set to approximately 30% of the maximum output current. Since the maximum output current of the TB7107FN is 2.0 A, ΔI_L should be 0.6 A or so. The inductor should have a current rating greater than the peak output current of 2.3 A. If the inductor current rating is exceeded, the inductor becomes saturated, leading to an unstable DC-DC converter operation.

When $V_{IN} = 12$ V and $V_{OUT} = 3.3$ V, the required inductance can be calculated as follows. Be sure to select an appropriate inductor, taking the input voltage range into account.

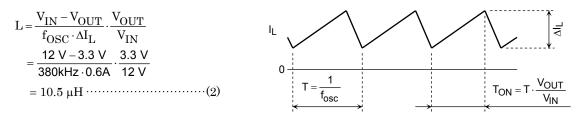


Figure 2 Inductor Current Waveform

Setting the Output Voltage

A resistive voltage divider is connected as shown in Figure 3 to set the output voltage; it is given by Equation 3 based on the reference voltage of the error amplifier (0.8 V typ.), which is connected to the Feedback pin, VFB. RFB1 should be up to 30 k Ω or so, because an extremely large-value RFB1 incurs a delay due to parasitic capacitance at the VFB pin. It is recommended that resistors with a precision of ±1% or higher be used for RFB1 and RFB2.



Figure 3 Output Voltage Setting Resistors

Setting the Phase Compensation Circuit

Connect a resister (RP) in series with a capacitor (CP) to COMP pin as a phase compensation. The following calculated value provides an estimation of the constant of phase compensation.

F0=Frequency in loop gain being 0dB

: Set approximately to one-tenth of the switching frequency

Fz=Frequency of pole-zero

: Set approximately to one-tenth of the F0

Design value (reference):

 $Gm(EA)=Error Amp Gm : 200(\mu S)$

Gm(IS)=Current detection circuit Gm : 4(S)

The optimum value of phase compensation may change with the characteristics of $C_{\mbox{OUT}}$ and another. Carry out sufficient evaluation on an actual operating condition.

Output Filter Capacitor Selection

Use a low-ESR electrolytic or ceramic capacitor as the output filter capacitor. Since a capacitor is generally sensitive to temperature, choose one with excellent temperature characteristics. The large capacitance improves load response characteristics. As a rule of thumb, its capacitance should be 10 μ F or greater for applications. The capacitance should be set to an optimal value that meets the system's ripple voltage requirement and transient load response characteristics. Since the ceramic capacitor has a very low ESR value, it helps reduce the output ripple voltage; however, because the ceramic capacitor provides less phase margin, it should be thoroughly evaluated.

Rectifier Selection

A Schottky barrier diode should be externally connected to the TB7107FN as a rectifier between the Lx and GND pins. It is recommended that either CMS02 or CRS15, be used as the Schottky barrier diode. If a large voltage overshoot is on the Lx pin, it reduces the voltage to connect a series CR network consisting of a resistor of $R_S = 4.7 \Omega$ and a capacitor of $C_S = 470 \text{ pF}$ with the Schottky barrier diode in parallel. Power loss of the Schottky barrier diode tends to increase due to an increased reverse current caused by the rise in ambient temperature and self-heating due to a supplied current. The rated current should therefore be derated to allow for such conditions in selecting an appropriate diode.

Soft-Start Feature

The TB7107FN has a soft-start feature.

If the SS pin is left open, the soft-start time, tSS, for VOUT defaults to 1 ms (typ.) internally.

The soft-start time can be extended by adding an external capacitor (CSS) between the SS and GND pins. The soft-start time can be calculated as follows:

	t_{SS2} :	Soft-start time (in seconds) when an external capacitor is
$t_{SS2} = 0.16 \cdot C_{SS}$ (5)		connected between SS and GND.
	C_{SS} :	Capacitor value (µF)

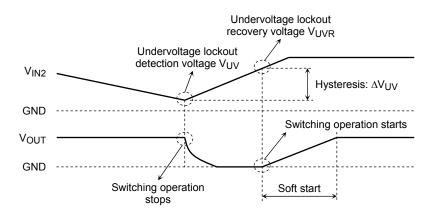
The soft-start feature is activated when the TB7107FN exits the undervoltage lockout (UVLO) state after power-up and when the voltage at the EN pin has changed from logic low to logic high.

Overcurrent Protection (OCP)

The TB7107FN has built-in overcurrent protection with pulse skip. When the peak current of Lx pin exceeds $I_{LIM}=3.5A(typ.)$, the ON time of the high-side switch(internal) will be limited. Switching frequency will be reduced and output current will be restricted further if output voltage falls and the voltage of VFB pin drops below the overcurrent pulse skip detection voltage V_{LOC} (0.3V typ.) during overcurrent protection.

Undervoltage Lockout (UVLO)

The TB7107FN has undervoltage lockout (UVLO) protection circuitry. The TB7107FN does not provide output voltage (V_{OUT}) until the input voltage has reached V_{UVR} (3.5 V typ.). UVLO has hysteresis of 0.3 V (typ.). After the switch turns on, if V_{IN} drops below V_{UV} (3.2 V typ.), UVLO shuts off the switch at V_{OUT}.





Thermal Shutdown (TSD)

The TB7107FN provides thermal shutdown. When the junction temperature continues to rise and reaches T_{SD} (160°C typ.), the TB7107FN goes into thermal shutdown and shuts off the power supply. TSD has a hysteresis of about 15°C (typ.). The device is enabled again when the junction temperature has dropped by approximately 15°C from the TSD trip point. The device resumes the power supply when the soft-start circuit is activated upon recovery from TSD state.

Thermal shutdown is intended to protect the device against abnormal system conditions. It should be ensured that the TSD circuit will not be activated during normal operation of the system.

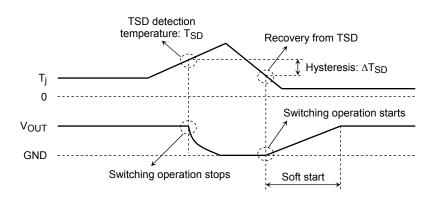
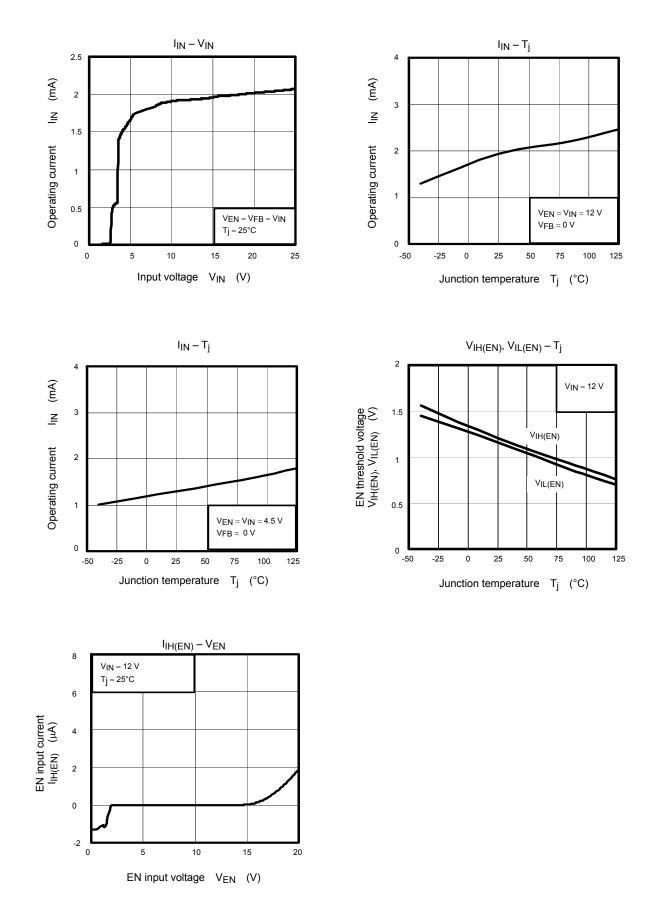


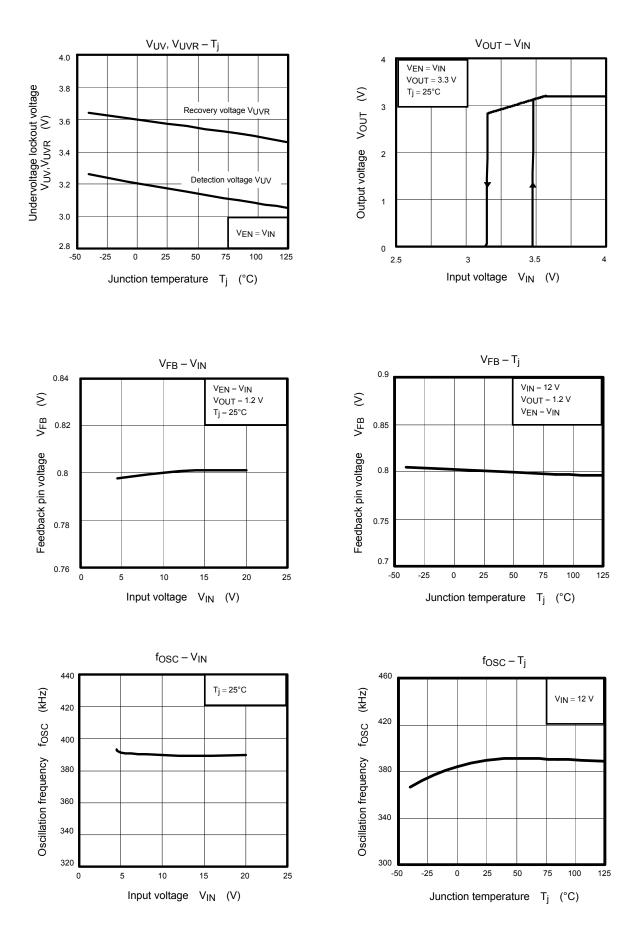
Figure 5 Thermal Shutdown Operation

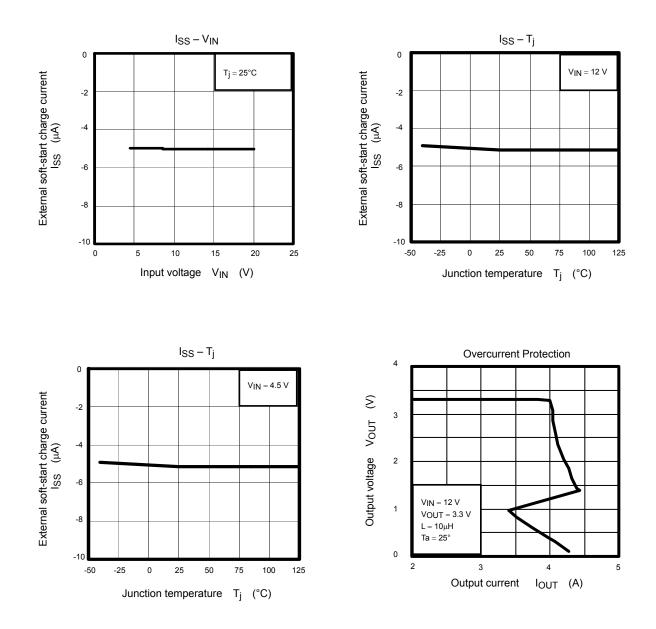
Usage Precautions

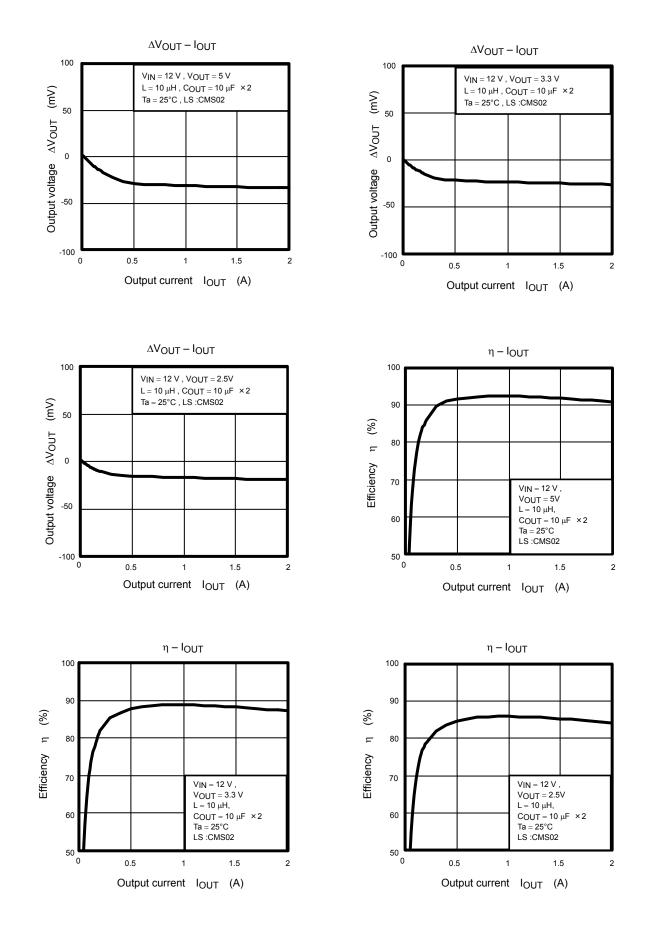
- The input voltage, output voltage, output current and temperature conditions should be considered when selecting capacitors, inductors and resistors. These components should be evaluated on an actual system prototype for best selection.
- External components such as capacitors, inductors and resistors should be placed as close to the TB7107FN as possible.
- $C_{\rm IN}$ should be connected as close to the GND and $V_{\rm IN1}$ pins as possible. Operation might become unstable due to board layout.
- The minimum programmable output voltage is 0.8 V (typ.). If the difference between the input and output voltages is small, the output voltage might not be regulated accurately and fluctuate significantly.
- GND pin is connected with the back of IC chip and serves as the heat radiation pin. Secure the area of a GND pattern as large as possible for greater of heat radiation.
- The overcurrent protection circuits in the Product are designed to temporarily protect Product from minor overcurrent of brief duration. When the overcurrent protective function in the Product activates, immediately cease application of overcurrent to Product. Improper usage of Product, such as application of current to Product exceeding the absolute maximum ratings, could cause the overcurrent protection circuit not to operate properly and/or damage Product permanently even before the protection circuit starts to operate.
- The thermal shutdown circuits in the Product are designed to temporarily protect Product from minor overheating of brief duration. When the overheating protective function in the Product activates, immediately correct the overheating situation. Improper usage of Product, such as the application of heat to Product exceeding the absolute maximum ratings, could cause the overheating protection circuit not to operate properly and/or damage Product permanently even before the protection circuit starts to operate.

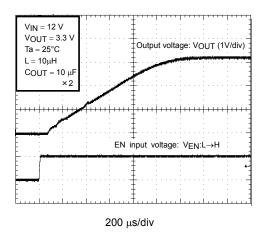
Typical Performance Characteristics



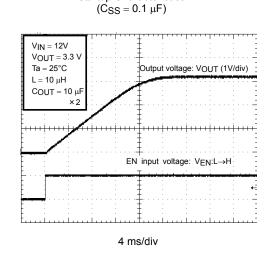






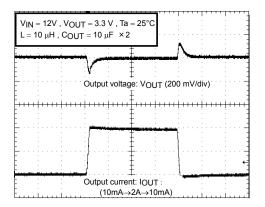


Startup Characteristics (Internal Soft-Start Time)



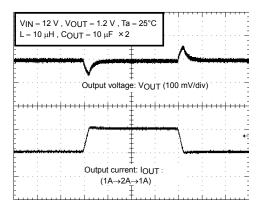
Startup Characteristics

Load Response Characteristics



200 µs/div

Load Response Characteristics



200 µs/div

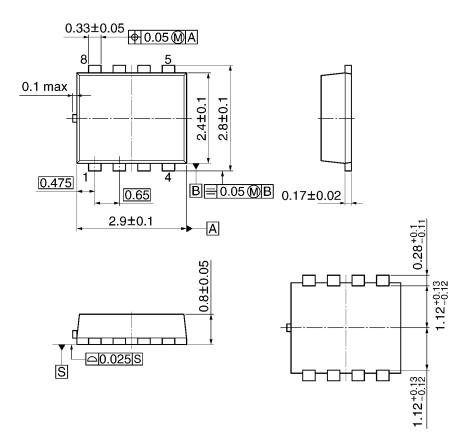


TB7107FN

Package Dimensions

SON8-P-0303-0.65A

Unit: mm



Weight: 0.017 g (typ.)

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